



日本電子機械工業会規格
Standard of Electronic Industries Association of Japan

EIAJ ED-7311-9A

集積回路パッケージ個別規格
[P-BGA(キャビティアップタイプ)]
Standards of integrated circuits package
[P-BGA(cavity up type)]

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作 成

半導体パッケージ標準化委員会
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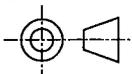
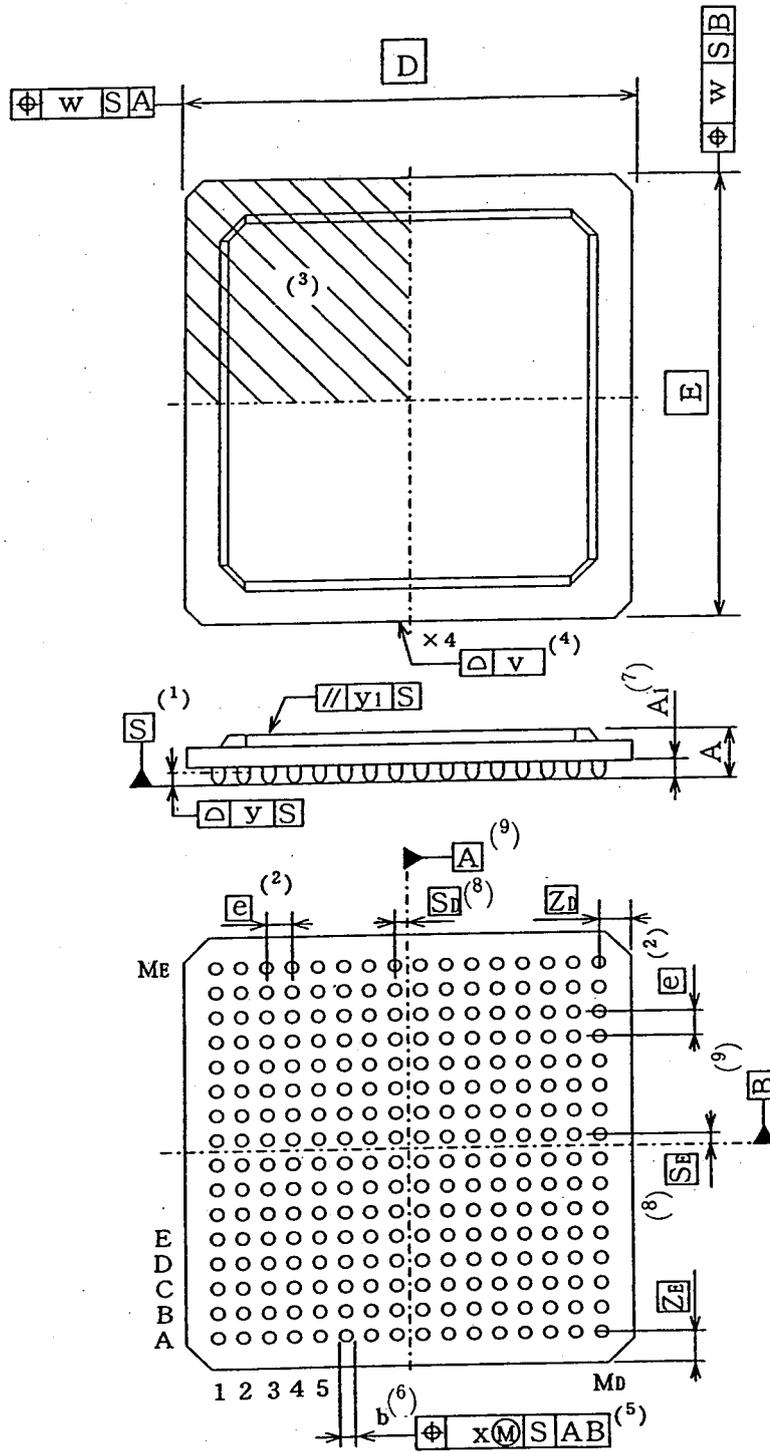
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照合文字と図面
Reference symbol and schematics

図1
Figure 1



EIAJ STANDARD
PACKAGE OUTLINE DRAWING

DATE
97-10-31

SHEET
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PACKAGE NAME
P-BGA

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